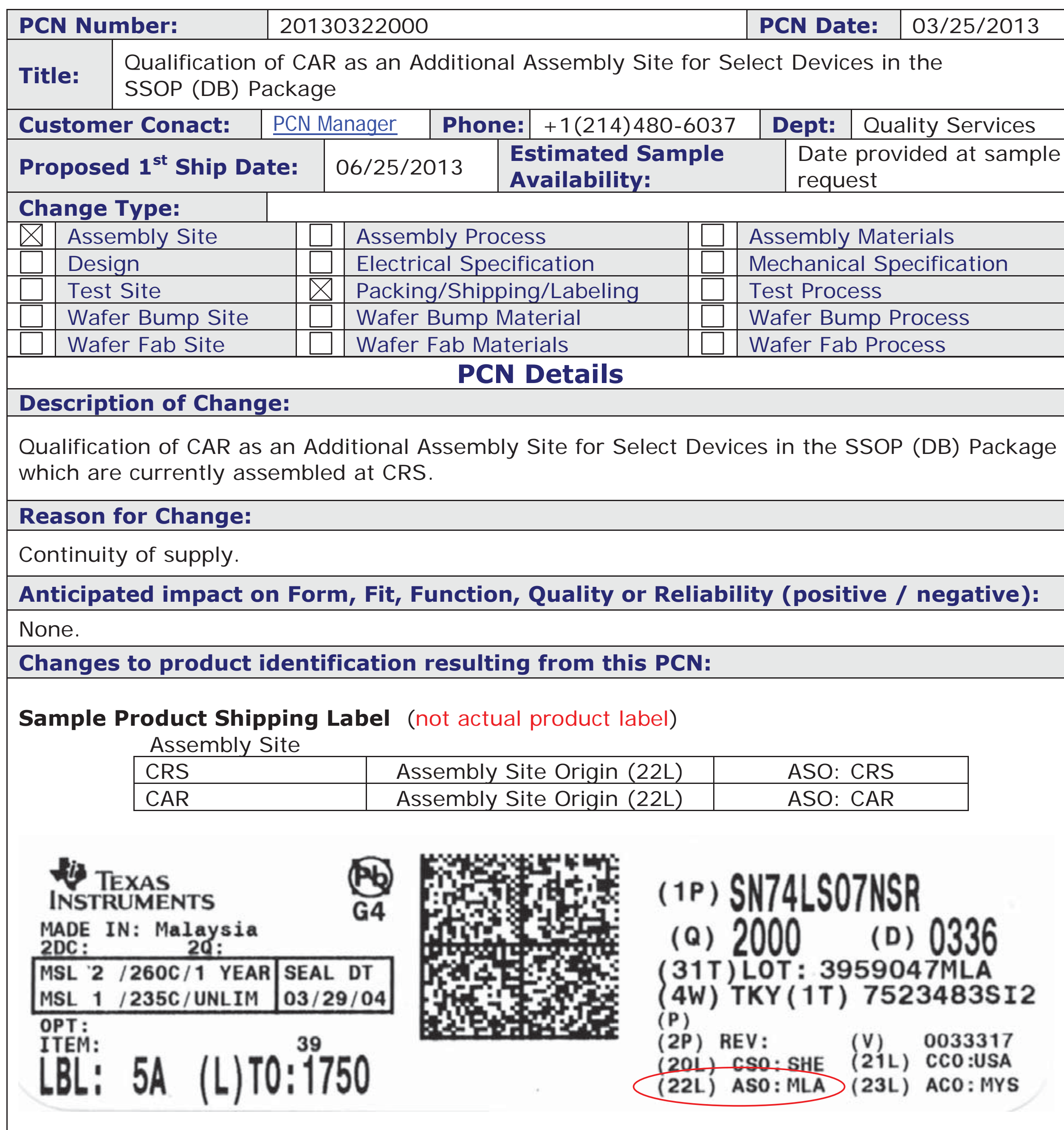

PCN Number:	20130322000	**PCN Date:**	03/25/2013
Title:	Qualification of CAR as an Additional Assembly Site for Select Devices in the SSOP (DB) Package		

Customer Conact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	06/25/2013	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☒	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Qualification of CAR as an Additional Assembly Site for Select Devices in the SSOP (DB) Package which are currently assembled at CRS.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Assembly Site

CRS	Assembly Site Origin (22L)	ASO: CRS
CAR	Assembly Site Origin (22L)	ASO: CAR

Product Affected:			
DAC7613E	DAC7615E	DAC7617E	DAC7631E
DAC7613EB	DAC7615EB	DAC7617EB	DAC7631EB
DAC7613EBG4	DAC7615EBG4	DAC7617EBG4	DAC7631EBG4
DAC7613EG4	DAC7615EG4	DAC7617EG4	DAC7631EG4
DAC7614E	DAC7616E	DAC7621E	DAC7731E
DAC7614EB	DAC7616EB	DAC7621EB	DAC7731EC
DAC7614EBG4	DAC7616EBG4	DAC7621EBG4	DAC7731ECG4
DAC7614EG4	DAC7616EG4	DAC7621EG4	DAC7731EG4

DB Qualification Data: Approved 3/21/2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device 1 : ADS1213E (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size Pass/Fail
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 2 : ADS7871IDB (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR	Mold Compound:	438358
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size/Fail
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 3 : ADS825E (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size/Fail
Solderability	Pb-Free/Solder	22/0
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Physical Dimensions	Mechanical drawing	5/0
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0
Notes: ** Preconditioning sequence Level 2-260C		

Qual Device 4 : DAC8820IBDB (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR	Mold Compound:	438518
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
Manufacturability	(Assembly Site)	Pass	Pass	Pass
Solderability	8 Hrs/Stm Age, Pb-Free/Solder	22/0	22/0	-
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Physical Dimensions	Mechanical drawing	5/0	-	-
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0	12/0	-
Notes: ** Preconditioning sequence Level 2-260C				

Qual Device 5 : PGA2505IDB (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	24-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size/Fail
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Physical Dimensions	Mechanical drawing	5/0
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0
Notes: ** Preconditioning sequence Level 2-260C		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com